## **EAST Search History**

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3	(devid\$3 separat\$3 remov\$3 peel\$3 releas\$3) with (substrate wafer) with ferroelectric) and (etch\$3 with (buffer sacrificial releas\$3) and (support\$4 with (substrate wafer material layer film)) and adhes\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/12 18:03
L2	5	((attach\$3 bond\$3 join\$3) with ferroelectric with (wafer substrate) with adhesive) and ((remove detach\$3 separat\$3) with support\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR ·	ON	2006/09/12 19:35
L3	5	((attach\$3 bond\$3 join\$3) with ferroelectric with (wafer substrate) with adhesive) and ((remov\$3 detach\$3 separat\$3) with support\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/12 18:10
L4	4	((attach\$3 bond\$3 join\$3) with ferroelectric with (wafer substrate) with adhesive) and ((remov\$3 detach\$3 separat\$3) with handl\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/12 18:29
L5	4	((attach\$3 bond\$3 join\$3) with ferroelectric with (wafer substrate) with adhesive) and ((remov\$3 detach\$3 separat\$3) with (support\$4 handl\$3) with (substrate wafer))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/12 18:35
L6	79	((remov\$3 detach\$3 separat\$3 release) with (support\$4 handl\$3) with ferroelectric)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/12 18:58
L7	5	6 and((attach\$3 bond\$3 join\$3) with ferroelectric with (wafer substrate) with adhesive)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/12 18:59

## **EAST Search History**

L8	109	((remov\$3 detach\$3 separat\$3 release) with (support\$4 handl\$3 carrier) with ferroelectric)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/12 19:41
L9	5	8 and((attach\$3 bond\$3 join\$3) with ferroelectric with (wafer substrate) with adhesive)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/12 19:18
L10	8046	438/3,118,240,458,464,745.ccls. "E21.6" "E21.601"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/12 19:17
L11	1	10 and((attach\$3 bond\$3 join\$3) with ferroelectric with (wafer substrate) with adhesive)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/12 19:33
L12	12	10 and ((remov\$3 detach\$3 separat\$3 release) with (support\$4 handl\$3 carrier) with ferroelectric)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/12 19:33
L13	281	((iwashita near setsuya) (higuchi near takamitsu) (miyazawa near hiromu)).in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/12 19:32
L14	1	13 and((attach\$3 bond\$3 join\$3) with ferroelectric with (wafer substrate) with adhesive)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/12 19:33

## **EAST Search History**

L15	1	13 and ((remov\$3 detach\$3 separat\$3 release) with (support\$4 handl\$3 carrier) with ferroelectric)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/12 19:35
L16	155089	(seiko near epson)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/12 19:35
L17	0	16 and ((attach\$3 bond\$3 join\$3) with ferroelectric with (wafer substrate) with adhesive) and ((remove detach\$3 separat\$3 releas\$3) with ferroelectric with (carrier handl\$3 support\$3))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/12 19:39
L19	1	(substrate and (buffer sacrificial) and ferroelectric and (remov\$3 detach\$3 separat\$3 release) and (support\$4 handl\$3 carrier) and adhesive).clm.	US-PGPUB	OR	ON	2006/09/12 19:45
L20	1	(substrate and (buffer sacrificial) and ferroelectric and etch\$3 and remov\$3 and separat\$3 and support\$4 and adhesive).clm.	US-PGPUB	OR	ON	2006/09/12 19:46

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